

What is claimed is:

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An alcohol-free antibacterial wipe comprising:
a flexible fabric substrate containing a latex binder; and
an aqueous antibacterial solution,
wherein said aqueous antibacterial solution is comprised of an
effective amount of a cationic antibacterial agent and a sufficient
amount of a surfactant and said binder is present in at least about
90% of the substrate thickness.

2. The wipe of claim 1 wherein the substrate is further comprised of a
front surface and a back surface, and said binder is present on both of
the surfaces.

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3. The alcohol-free antibacterial wipe of claim 1 wherein
said flexible fabric substrate is comprised of rayon,
said cationic antibacterial agent is benzalkonium chloride, and
said surfactant is disodium lauroamphodiacetate.

4. The alcohol-free antibacterial wipe of claim 2 wherein the effective
amount of benzalkonium chloride is, based upon the total weight of
the aqueous antibacterial solution, from about 0.09% to about 0.15%.

5. The wipe of claim 1 wherein the binder is a polymer latex polymerized
from at least one acrylic monomer.

6. The wipe of claim 1 wherein the binder is a polymer latex comprised of a mixture of a self-crosslinking acrylic emulsion polymer latex binder and an acrylic emulsion polymer latex binder.

5 SUB A2 7. A method of preparing an alcohol-free antibacterial wipe which comprises

- (i) preparing a solution of a cationic antibacterial agent, a surfactant, and water; and
- (ii) applying said solution onto a flexible fabric substrate containing a latex binder, wherein said binder is present in at least about 90% of the substrate thickness.

8. The method of claim 7 which further comprises

- (i) preparing a solution of, based upon the total weight of the solution, from about 0.21% to about 0.22% benzalkonium chloride, about 0.15% to about 0.3% disodium lauroamphodiacetate, and water; and
- (ii) applying said solution onto a substrate comprised of rayon and containing a latex binder, wherein said binder is present in at least about 90% of the substrate thickness.